

Amendments to the Specification

Please revise the paragraph at page 3, lines 6-9, as follows:

According to an aspect of the present invention, there is provided a cleaning solution comprising about 5-30% by weight of fluoric salt, and about 20-10% by weight of organic acid, about 30-50% by weight of organic solvent, and about 50% 20-50% by weight of water.

Please revise the paragraph at page 3, lines 10-15, as follows:

According to another aspect of the present invention, there is provided a method of cleaning ceramic parts on which plasma reaction by-products are adsorbed. The ceramic parts are dipped into a cleaning solution including about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about 50% 20-50% by weight of water. After rinsing the ceramic parts, the ceramic parts are treated with heat.

Please revise the paragraph at page 3, lines 16-25, as follows:

According to still another aspect of the present invention, there is provided a method of cleaning ceramic parts on which etching by-products are adsorbed as the result of etching a layer formed on a semiconductor substrate after introducing the substrate into a dry etching apparatus containing the ceramic parts. The method includes dipping the ceramic parts into a first cleaning solution including about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about 50% 20-50% by weight of water after separating the ceramic parts from the etching apparatus, and then dipping the ceramic parts into a second cleaning solution of sodium hydroxide aqueous solution. After rinsing the ceramic parts, the ceramic parts are treated with heat.

Please revise the paragraph at page 9, lines 14-16, as follows:

The cleaning solution of the present invention includes about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about 50% 20-50% by weight of water.

Please amend the Abstract of the Disclosure as follows (a clean copy of the revised Abstract is submitted herewith on a separate page 11 of this paper):

Plasma reaction by products are removed from ceramic parts of semiconductor fabrication equipment by dipping the ceramic parts into a cleaning solution, rinsing the ceramic parts, and treating the ceramic parts with heat. The cleaning Cleaning solution is used to clean ceramic parts using the same. The cleaning solution includes about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about 50% 20-50% by weight of water. The ceramic parts may be portions of an etching apparatus on which plasma reaction by-products are adsorbed. Plasma reaetion by products are removed from the ceramic parts dipping the parts into the cleaning solution, followed by rinsing and heat treatment.